

Claims

1. A tin-silver based lead-free solder, characterized by:
containing zinc (Zn) added to a solder comprising a tin-silver system containing no lead.
2. The tin-silver based lead-free solder according to claim 1, characterized by
further containing indium (In) added thereto.
3. The tin-silver based lead-free solder according to claim 1, characterized in that
an amount of zinc (Zn) added is 0.3 to 1.0 wt.%, a remainder being tin and silver.
4. The tin-silver based lead-free solder according to claim 2, characterized in that
an amount of indium (In) added is less than 10 wt.%, and an amount of zinc (Zn) added is 0.1 to 1.0 wt.%, a remainder being tin and silver.
5. A joint structure, characterized in that
bodies to be joined are joined together by the tin-silver based lead-free solder of any one of claims 1 to 4.

6. The joint structure according to claim 5,
characterized in that

an electroless plating layer is provided on
surfaces of said bodies to be joined.

7. The joint structure according to claim 6,
characterized in that

said electroless plating layer is a Ni-P plating.
